

2SK3064

Silicon N-channel MOSFET

For switching circuit

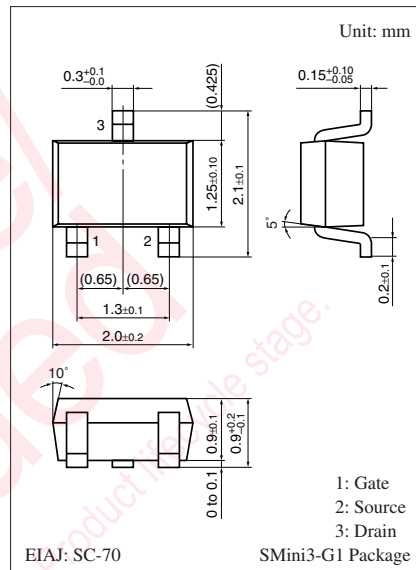
For rechargeable battery pack (Li⁺ ion battery, etc.)

■ Features

- High gate-source voltage (Drain open) V_{GSO}
- Low gate threshold voltage V_{th}

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Drain-source surrender voltage	V_{DSS}	30	V
Gate-source voltage (Drain open)	V_{GSO}	± 20	V
Drain current	I_D	100	mA
Peak drain current	I_{DP}	200	mA
Power dissipation	P_D	150	mW
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$



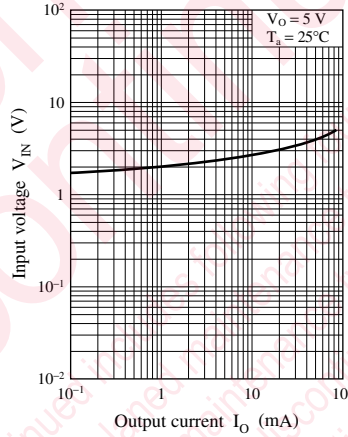
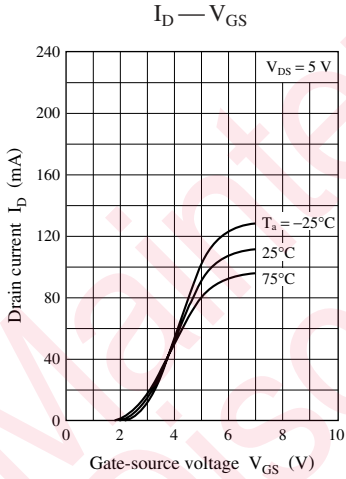
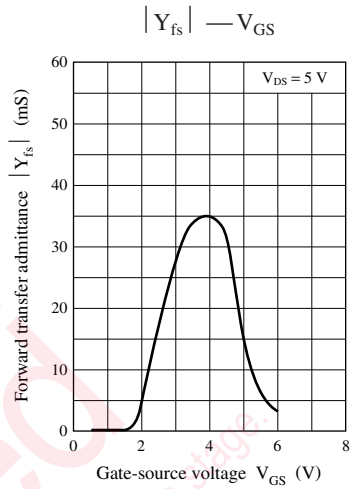
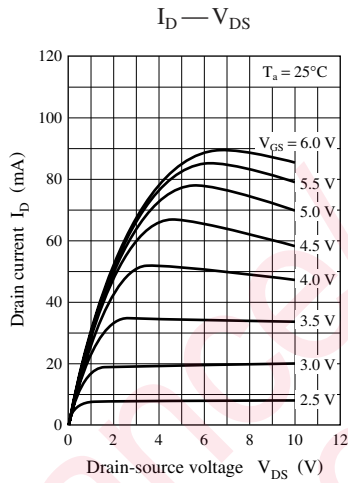
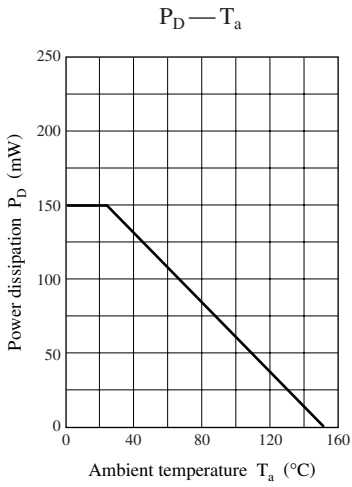
Marking symbol: 2D

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source cutoff current	I_{DSS}	$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}$			0.1	μA
Gate-source cutoff current	I_{GSS}	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$			± 1.0	μA
Gate threshold voltage	V_{th}	$V_{DS} = 5\text{ V}, I_D = 1\text{ }\mu\text{A}$	1.0		2.0	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 5\text{ V}, I_D = 10\text{ mA}$	15			mS
ON resistance	R_{on}	$V_{GS} = 5\text{ V}, I_D = 10\text{ mA}$		30	50	Ω
Turn-on time	t_{on}	$V_{DD} = 5\text{ V}, V_{GS} = 0\text{ V to } 5\text{ V}$ $R_L = 200\text{ }\Omega$		150		ns
Turn-off time	t_{off}	$V_{DD} = 5\text{ V}, V_{GS} = 5\text{ V to } 0\text{ V}$ $R_L = 200\text{ }\Omega$		35		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. Observe precautions for handling. Electrostatic sensitive devices.



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